

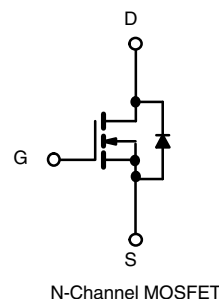
Automotive N-Channel 60 V (D-S) 175 °C MOSFET

PowerPAK® SO-8L Single


FEATURES

- TrenchFET® power MOSFET
- AEC-Q101 qualified
- 100 % R_g and UIS tested
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

AUTOMOTIVE
GRADE

RoHS
COMPLIANT
HALOGEN
FREE


PRODUCT SUMMARY	
V_{DS} (V)	60
$R_{DS(on)}$ (Ω) at $V_{GS} = 10$ V	0.0320
I_D (A) per leg	15
Configuration	Single
Package	PowerPAK SO-8L

ABSOLUTE MAXIMUM RATINGS ($T_C = 25$ °C, unless otherwise noted)				
PARAMETER		SYMBOL	LIMIT	UNIT
Drain-source voltage		V_{DS}	60	V
Gate-source voltage		V_{GS}	± 20	
Continuous drain current ^a	$T_C = 25$ °C	I_D	15	A
	$T_C = 125$ °C		15	
Continuous source current (diode conduction) ^a		I_S	15	
Pulsed drain current ^b		I_{DM}	40	
Single pulse avalanche current	L = 0.1 mH	I_{AS}	13	
Single pulse avalanche energy		E_{AS}	8.4	mJ
Maximum power dissipation ^b	$T_C = 25$ °C	P_D	45	W
	$T_C = 125$ °C		15	
Operating junction and storage temperature range		T_J, T_{stg}	-55 to +175	°C
Soldering recommendations (peak temperature) ^{d, e}			260	

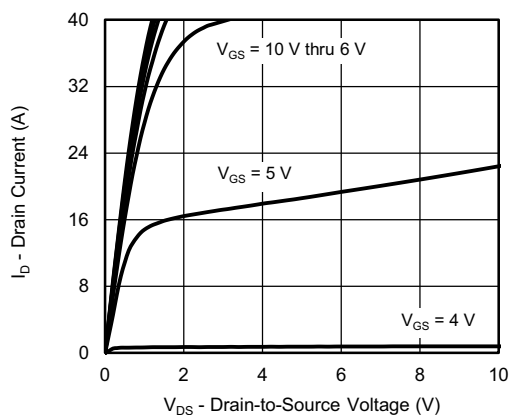
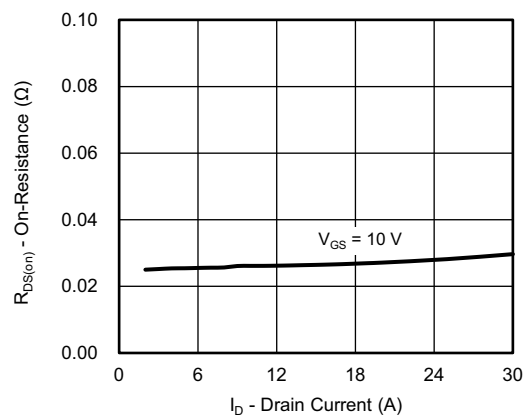
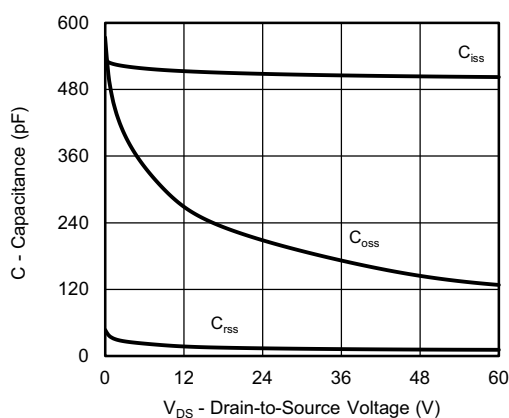
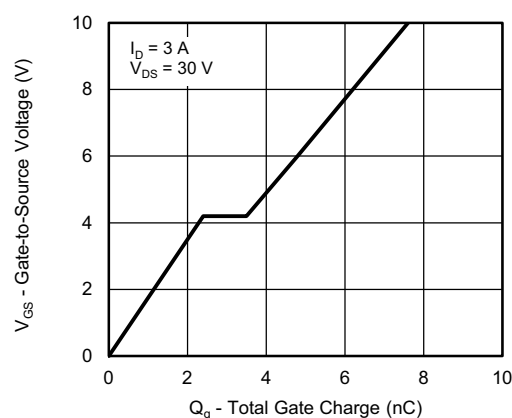
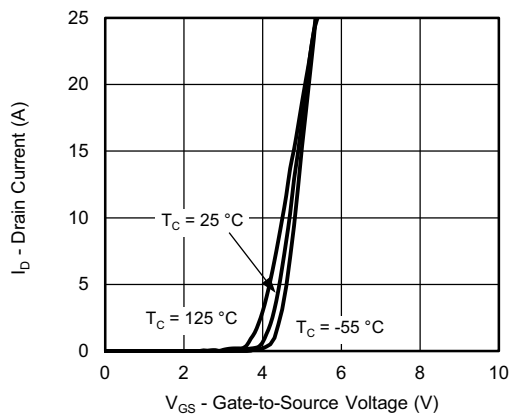
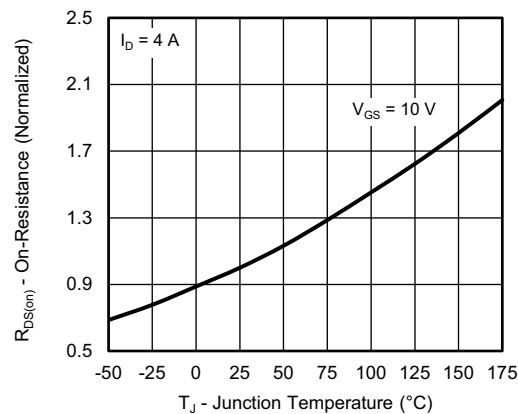
THERMAL RESISTANCE RATINGS				
PARAMETER		SYMBOL	LIMIT	UNIT
Junction-to-ambient	PCB mount ^c	R_{thJA}	70	°C/W
Junction-to-case (drain)		R_{thJC}	3.3	

Notes

- Package limited
- Pulse test; pulse width $\le$

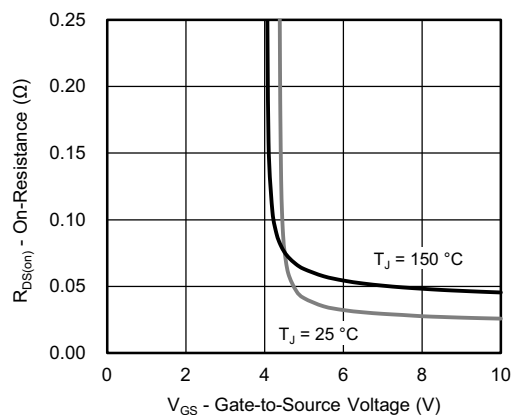


SPECIFICATIONS ($T_C = 25\text{ }^{\circ}\text{C}$, unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-source breakdown voltage	V_{DS}	$V_{GS} = 0\text{ V}$, $I_D = 250\text{ }\mu\text{A}$		60	-	-	V
Gate-source threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = 250\text{ }\mu\text{A}$		2.5	3.0	3.5	
Gate-source leakage	I_{GSS}	$V_{DS} = 0\text{ V}$, $V_{GS} = \pm 20\text{ V}$		-	-	± 100	nA
Zero gate voltage drain current	I_{DSS}	$V_{GS} = 0\text{ V}$	$V_{DS} = 60\text{ V}$	-	-	1	μA
		$V_{GS} = 0\text{ V}$	$V_{DS} = 60\text{ V}$, $T_J = 125\text{ }^{\circ}\text{C}$	-	-	50	
		$V_{GS} = 0\text{ V}$	$V_{DS} = 60\text{ V}$, $T_J = 175\text{ }^{\circ}\text{C}$	-	-	150	
On-state drain current ^a	$I_{D(on)}$	$V_{GS} = 10\text{ V}$	$V_{DS} \geq 5\text{ V}$	5	-	-	A
Drain-source on-state resistance ^a	$R_{DS(on)}$	$V_{GS} = 10\text{ V}$	$I_D = 4\text{ A}$	-	0.0259	0.0320	Ω
		$V_{GS} = 10\text{ V}$	$I_D = 4\text{ A}$, $T_J = 125\text{ }^{\circ}\text{C}$	-	-	0.0527	
		$V_{GS} = 10\text{ V}$	$I_D = 4\text{ A}$, $T_J = 175\text{ }^{\circ}\text{C}$	-	-	0.0650	
Forward transconductance ^b	g_{fs}	$V_{DS} = 15\text{ V}$, $I_D = 4\text{ A}$		-	13	-	S
Dynamic ^b							
Input capacitance	C_{iss}	$V_{GS} = 0\text{ V}$	$V_{DS} = 25\text{ V}$, $f = 1\text{ MHz}$	-	508	670	pF
Output capacitance	C_{oss}			-	206	270	
Reverse transfer capacitance	C_{rss}			-	14	20	
Total gate charge ^c	Q_g	$V_{GS} = 10\text{ V}$	$V_{DS} = 30\text{ V}$, $I_D = 3\text{ A}$	-	7.6	12	nC
Gate-source charge ^c	Q_{gs}			-	2.4	-	
Gate-drain charge ^c	Q_{gd}			-	1.1	-	
Gate resistance	R_g	$f = 1\text{ MHz}$		0.5	1.1	1.7	Ω
Turn-on delay time ^c	$t_{d(on)}$	$V_{DD} = 30\text{ V}$, $R_L = 20\text{ }\$					

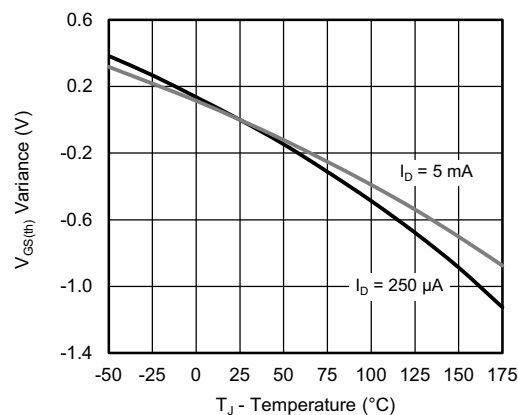
TYPICAL CHARACTERISTICS ($T_A = 25\text{ }^{\circ}\text{C}$, unless otherwise noted)

Output Characteristics

On-Resistance vs. Drain Current

Capacitance

Gate Charge

Transfer Characteristics

On-Resistance vs. Junction Temperature



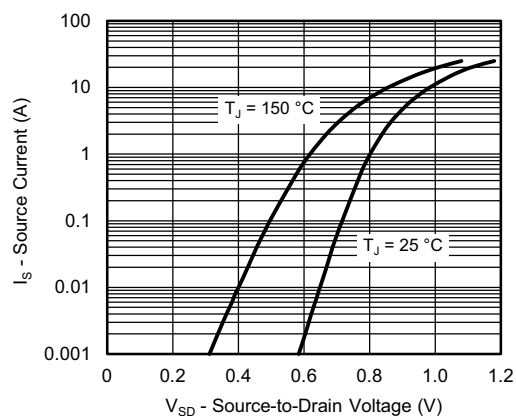
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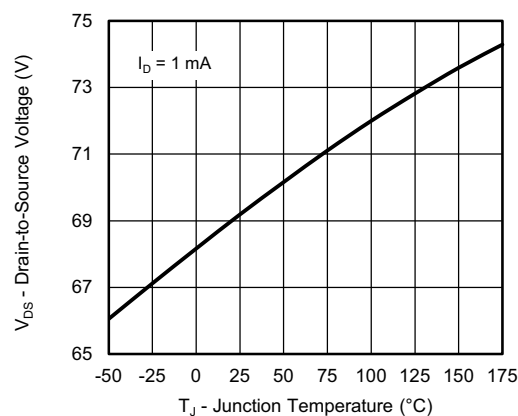
On-Resistance vs. Gate-to-Source Voltage



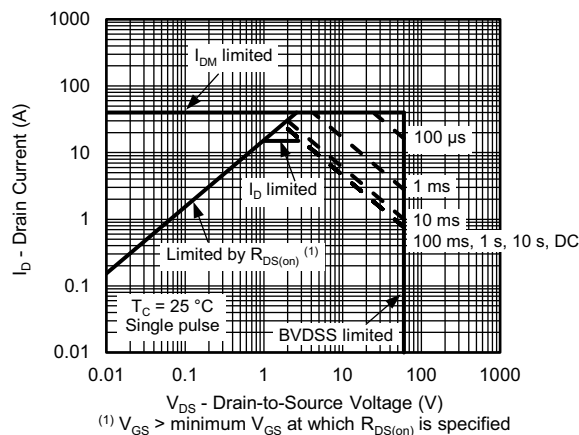
Threshold Voltage



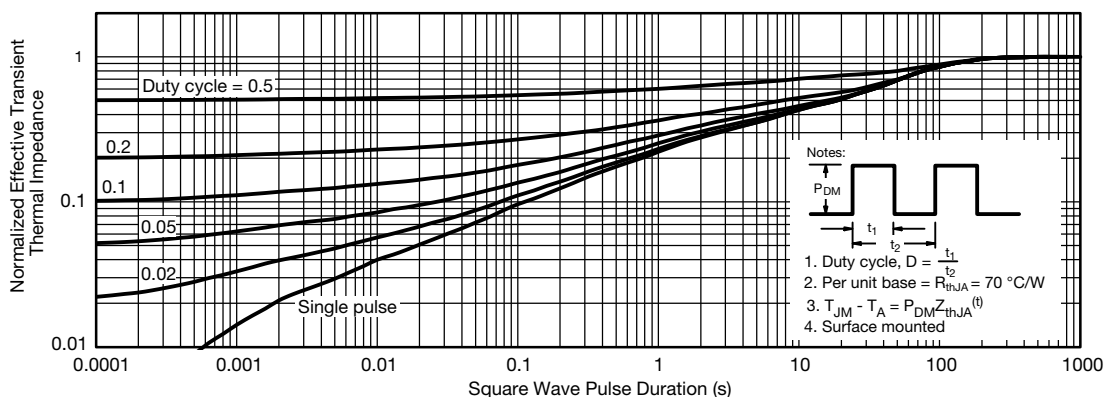
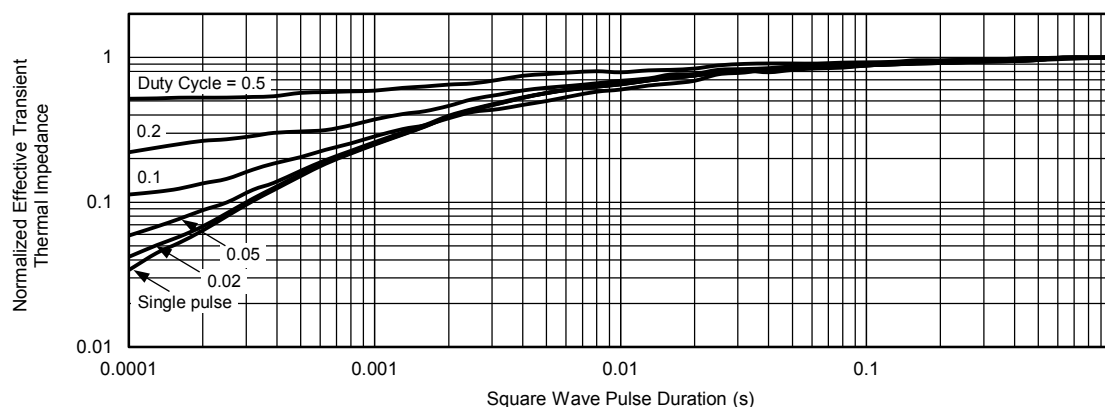
Source Drain Diode Forward Voltage



Drain Source Breakdown vs. Junction Temperature



Safe Operating Area

**THERMAL RATINGS** ($T_A = 25\text{ }^{\circ}\text{C}$, unless otherwise noted)**Normalized Thermal Transient Impedance, Junction-to-Ambient****Normalized Thermal Transient Impedance, Junction-to-Case****Note**

- The characteristics shown in the two graphs
 - Normalized Transient Thermal Impedance Junction-to-Ambient ($25\text{ }^{\circ}\text{C}$)
 - Normalized Transient Thermal Impedance Junction-to-Case ($25\text{ }^{\circ}\text{C}$)
- are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions

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